## [Time: 3 Hours]

[ Marks:80]

Please check whether you have got the right question paper.

N.B: 1. Q. 1 is compulsory.

- 2. Attempt any three out of remaining questions.
- 3. Assume suitable data wherever required and justify the same.

## Q.1 Attempt any four.

Q.1	Attempt any four.		000
	a)	What is MEMS? What is significant difference between Microelectronics and Microsystem?	20
	b)	Discuss the role of SU8 in MEMS applications.	
	c)	Define TCR & Stiffness and its significance wrt to MEMS	
	d)	What is Etch stop? Discuss it's techniques.	
	e)	Describe the phenomenon of Stiction, and possible ways to avoid it.	) De s
<b>Q.2</b>	a)	Discuss the process flow of Photolithography. Explain the types of photoresist used.	10
	b)	Explain silicon crystal structure. Why silicon is used as substrate material in MEMS?	10
Q.3	a)	Explain in details application of Polymers in MEMS. Why and How to make polymer conductive.	10
	b)	What are the design considerations in Selection of MEMS materials?	10
Q.4	a)	Describe the process flow for fabricating micro heater. Also explain its working principle.	10
	b)	List the types of pressure sensor and show the process steps for fabricating the piezoresistive pressure sensor.	10
Q.5	a)	What is MEMS micromachining? Explain in details fabrication process flow of LIGA. Why electroplating is necessary in LIGA process.	10
	b)	Compare Deposition techniques used in MEMS with respect to their applications.	10
Q.6	Write Short note on		20
	a) b)	Wire bonding MEMS Reliability	

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c) Annealing

d) Sensors in Biomedical Applications